

TO-272S-2

Rev. V2

#### **Features**

- Optimized for a Multitude of Applications
- CW and Pulsed Operation: 50 W Output Power
- Internally Pre-matched
- 260°C Reflow Compatible
- 50 V Operation
- 100% RF Tested
- RoHS\* Compliant



• military radio communications, digital cellular infrastructure, RF energy, avionics, test instrumentation and RADAR

#### Description

The MAPC-A1110-AP is a high power GaN on Silicon HEMT D-mode amplifier optimized for DC -2700 MHz frequency operation. The device supports both CW and pulsed operation with peak output power levels to 50 W (47 dBm) in a plastic package.

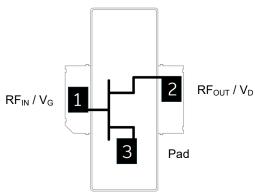
#### **Typical Performance:**

Measured in Evaluation Test Fixture: P<sub>IN</sub> = 32 dBm, 100 µs pulse width, 10% duty cycle

 $V_{DS} = 50 \text{ V}, I_{DQ} = 100 \text{ mA}, T_{C} = 25^{\circ}\text{C}$ 

Frequency (MHz)	Output Power (dBm)	Gain (dB)	η <sub>D</sub> (%)
2400	48.57	16.56	69
2450	48.63	16.63	72
2500	48.22	16.22	66

**Functional Schematic** 



## **Pin Configuration**

Pin#	Pin Name	Function
1	RF <sub>IN</sub> / V <sub>G</sub>	RF Input / Gate
2	RF <sub>OUT</sub> / V <sub>D</sub>	RF Output / Drain
3	Pad <sup>1</sup>	Ground / Source

1. The exposed pad centered on the package bottom must be connected to RF, DC and thermal ground.

#### **Ordering Information**

Part Number	Package
MAPC-A1110-AP000	Bulk Quantity
MAPC-A1110-APTR1	Tape and Reel
MAPC-A1110-APSB1	Sample Board

<sup>\*</sup> Restrictions on Hazardous Substances, compliant to current RoHS EU directive.



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#### RF Electrical Characteristics: $T_C = 25^{\circ}C$ , $V_{DS} = 50 \text{ V}$ , $I_{DQ} = 100 \text{ mA}$ Note: Performance in MACOM Application Fixture (2400 - 2500 MHz), 50 $\Omega$ system

Parameter	Test Conditions	Symbol	Min.	Тур.	Max.	Units
Small Signal Gain	CW, 2500 MHz G <sub>SS</sub>		-	18.8	-	dB
Power Gain	CW <sub>2</sub> , 2500 MHz, 2 dB Gain Compression	G <sub>SAT</sub>	-	16.6	-	dB
Saturated Drain Efficiency	CW <sub>2</sub> , 2500 MHz, 2 dB Gain Compression	$\eta_{SAT}$	-	65	-	%
Saturated Output Power	CW <sub>2</sub> , 2500 MHz, 2 dB Gain Compression P <sub>SAT</sub>		-	48.1	-	dBm
Gain Variation (-40°C to +85°C)	Pulsed <sup>2</sup> , 2500 MHz $\Delta$ G		-	0.005	-	dB/°C
Power Variation (-40°C to +85°C)	Pulsed <sup>2</sup> , 2500 MHz	ΔP2dB	-	0.005	-	dB/°C
Gain	CW <sub>2</sub> , 2500 MHz, P <sub>IN</sub> = 32 dBm	G <sub>P</sub>	-	16.2	-	dB
Drain Efficiency	CW <sub>2</sub> , 2500 MHz, P <sub>IN</sub> = 32 dBm	η	-	66	-	%
Ruggedness: Output Mismatch	All phase angles	Ψ		VSWR No Devic	t = 10:1, e Dama	

### RF Electrical Specifications: $T_A = 25^{\circ}C$ , $V_{DS} = 50 \text{ V}$ , $I_{DQ} = 100 \text{ mA}$ Note: Performance in MACOM Production Test Fixture, $50 \Omega$ system

Parameter	Test Conditions	Symbol	Min.	Тур.	Max.	Units
Power Gain	CW <sub>2</sub> , 2500 MHz, 2 dB Gain Compression G <sub>SAT</sub>		14.5	15.8	-	dB
Saturated Drain Efficiency	CW <sub>2</sub> , 2500 MHz, 2 dB Gain Compression η <sub>SAT</sub>		67	71		%
Saturated Output Power	CW <sub>2</sub> , 2500 MHz, 2 dB Gain Compression	P <sub>SAT</sub>	49	49.8	-	dBm
Gain	CW, 2500 MHz, P <sub>IN</sub> = 33 dBm	$G_P$	15.5	16.4	i	dB
Drain Efficiency	CW, 2500 MHz, P <sub>IN</sub> = 33 dBm	η	63	69	-	%

<sup>2.</sup> Pulse details: 100 µs pulse width, 1 ms period, 10% Duty Cycle.

## DC Electrical Characteristics T<sub>A</sub> = 25°C

Parameter	Test Conditions	Symbol	Min.	Тур.	Max.	Units
Drain-Source Leakage Current	$V_{GS}$ = -8 V, $V_{DS}$ = 130 V	I <sub>DLK</sub>	-	-	10.8	mA
Gate-Source Leakage Current	$V_{GS}$ = -8 V, $V_{DS}$ = 0 V	I <sub>GLK</sub>	-	-	10.8	mA
Gate Threshold Voltage	V <sub>DS</sub> = 50 V, I <sub>D</sub> = 10.8 mA	V <sub>T</sub>	-2.6	-2.0	-1.6	٧
Gate Quiescent Voltage	V <sub>DS</sub> = 50 V, I <sub>D</sub> = 250 mA	$V_{GSQ}$	-2.4	-1.8	-1.4	٧



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## Absolute Maximum Ratings<sup>3,4,5,6,7</sup>

Parameter	Absolute Maximum		
Drain Source Voltage, V <sub>DS</sub>	130 V		
Gate Source Voltage, V <sub>GS</sub>	-10 to 3 V		
Gate Current, I <sub>G</sub>	10 mA		
Storage Temperature Range	-65°C to +150°C		
Case Operating Temperature Range	-40°C to +120°C		
Channel Operating Temperature Range, T <sub>CH</sub>	-40°C to +225°C		
Absolute Maximum Channel Temperature	+250°C		

- 3. Exceeding any one or combination of these limits may cause permanent damage to this device.
- MACOM does not recommend sustained operation above maximum operating conditions.

- Operating at drain source voltage V<sub>DS</sub> < 55 V will ensure MTTF > 2.5 x 10<sup>6</sup> hours.
  Operating at nominal conditions with T<sub>CH</sub> ≤ 225°C will ensure MTTF > 2.5 x 10<sup>6</sup> hours.
  MTTF may be estimated by the expression MTTF (hours) = A e <sup>[B + C/(T+273)]</sup> where *T* is the channel temperature in degrees Celsius, A = 0.0355, B = -9.89, and C = 13,925.

#### Thermal Characteristics<sup>8</sup>

Parameter	Test Conditions	Symbol	Typical	Units
Thermal Resistance using Finite Element Analysis	$V_{DS} = 50 \text{ V}, P_{D} = 30 \text{ W},$ $T_{C} = 85^{\circ}\text{C}, T_{CH} = 225^{\circ}\text{C}$	$R_{\theta}(FEA)$	3.14	°C/W

<sup>8.</sup> Case temperature measured using thermocouple embedded in heat-sink. Contact local applications support team for more details on this

#### **Handling Procedures**

Please observe the following precautions to avoid damage:

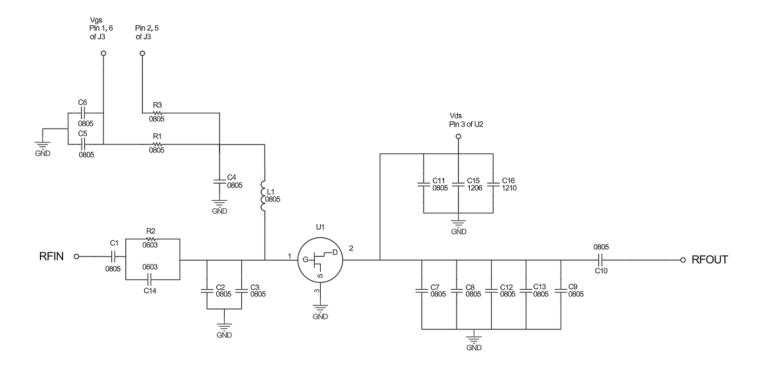
#### Static Sensitivity

Gallium Nitride Circuits are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these HBM Class 1B, CDM Class C3 devices.



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### Application Fixture 2400 - 2500 MHz



#### **Description**

Parts measured on application board (20-mil thick RF35A2). Matching is provided using a combination of lumped elements and transmission lines as schematic shown in the simplified above. Recommended tuning solution component placement, transmission lines, and details are shown on the next page.

#### **Bias Sequencing Turning the device ON**

- Set  $V_{GS}$  to pinch-off  $(V_P)$ .
- Turn on V<sub>DS</sub> to nominal voltage (50 V).
- Increase V<sub>GS</sub> until I<sub>DS</sub> current is reached.
- Apply RF power to desired level.

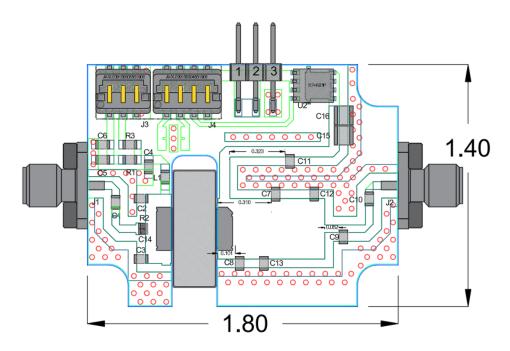
#### **Turning the device OFF**

- Turn the RF power off.
  Decrease V<sub>GS</sub> down to V<sub>P</sub> pinch-off.
  Decrease V<sub>DS</sub> down to 0 V.
- Turn off V<sub>GS</sub>.



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### Application Fixture 2400 - 2500 MHz



#### **Parts List**

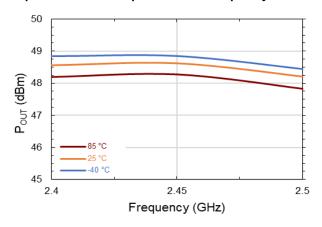
Reference Designator	Value	Tolerance	Manufacturer	Part Number
C1	22 pF	5%	Kyocera AVX	600F220JT250XT
C10	10 pF	5%	Kyocera AVX	600F100JT250XT
C11, C13	3 pF	0.1pF	Kyocera AVX	600F3R0BT250XT
C14	6.8 pF	0.1pF	Kyocera AVX	600S6R8BT250XT
C15	1 μF	10%	Murata	GRM32ER72A105KA01
C16	10 µF	10%	Murata	GRM32ER61H106KA12
C2, C3	1.1 pF	0.1pF	Kyocera AVX	600F1R1BT250XT
C4	4.7 pF	0.1pF	Kyocera AVX	600F4R7BT250XT
C5	0.01 μF	0.01uF	Murata	GRM21BR72E103KW03
C6	1 μF	10%	Murata	GCM21BC72A105KE36
C7, C8, C9, C12	1.8 pF	0.1pF	Kyocera AVX	600F1R8BT250XT
L1	12 nH	2%	Coilcraft	0805HP-12NXGRC
R1	5.1 Ω	1%	Yageo	RC0805FR-075R1L
R2	5.6 Ω	1%	Yageo	AC0603FR-075R6L
R3	1 kΩ	5%	VIKING	CR-050FLF1K
U2	80-V	-	MACOM	Si7469DP
Q1	50 W	-	MACOM	MAPC-A1110-AP
PCB	Taconic RF35A2, 20 mil, 1 oz. Cu, Au Finish			



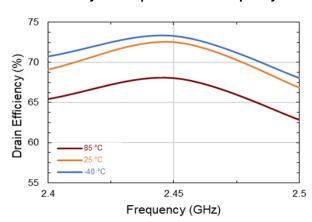
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Typical Performance Curves as Measured in the 2400 - 2500 MHz Application Fixture: CW, 2.45 GHz,  $V_{DS}$  = 50 V,  $I_{DQ}$  = 100 mA,  $T_{C}$  = 25°C Unless Otherwise Noted

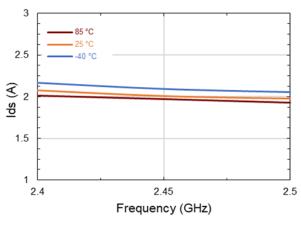
#### Output Power vs. Temperature and Frequency



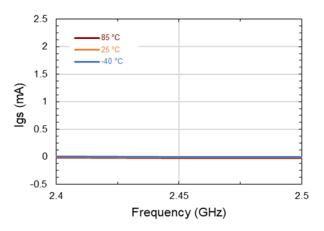
#### Drain Efficiency vs Temperature and Frequency



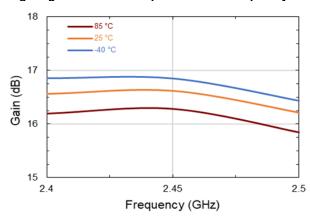
#### Drain Current vs. Temperature and Frequency



Gate Current vs. Temperature and Frequency



#### Large Signal Gain vs. Temperature and Frequency

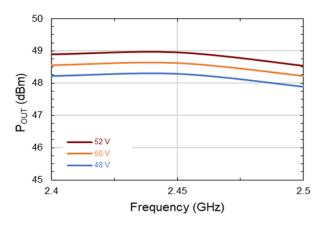




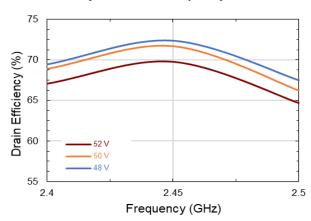
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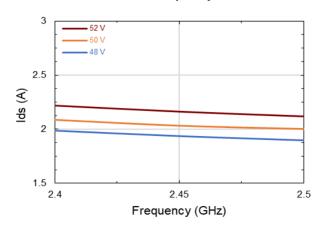
#### Output Power vs. VDS and Frequency



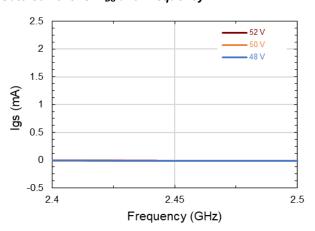
#### Drain Efficiency vs. V<sub>DS</sub> and Frequency



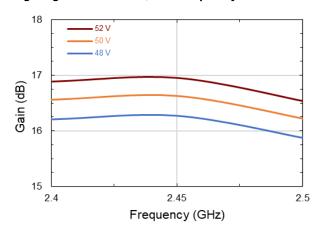
#### Drain Current vs. V<sub>DS</sub> and Frequency



Gate Current vs. V<sub>DS</sub> and Frequency



#### Large Signal Gain vs. VDS and Frequency

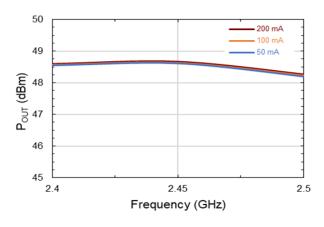




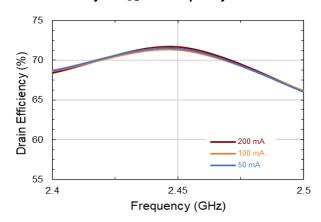
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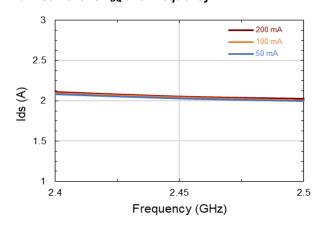
#### Output Power vs. IDQ and Frequency



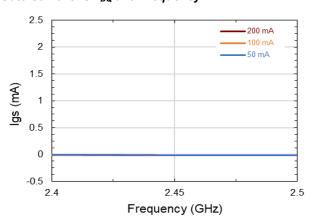
#### Drain Efficiency vs. I<sub>DQ</sub> and Frequency



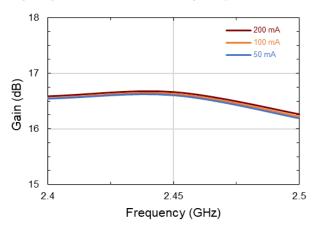
#### Drain Current vs. IDQ and Frequency



Gate Current vs. IDQ and Frequency



#### Large Signal Gain vs. IDQ and Frequency

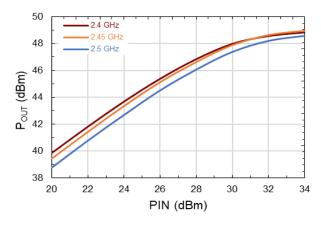




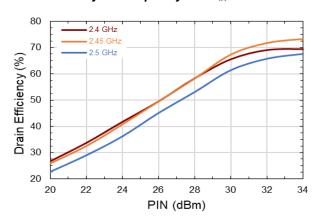
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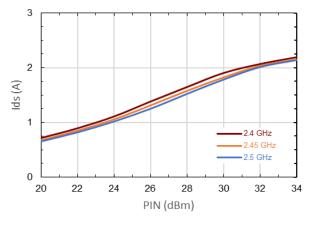
#### Output Power vs. Frequency and PIN



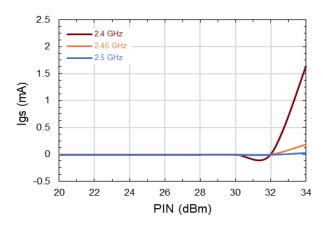
#### Drain Efficiency vs. Frequency and PIN



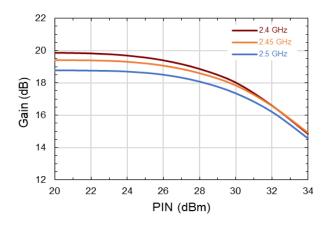
#### Drain Current vs. Frequency and PIN



Gate Current vs. Frequency and PIN



#### Large Signal Gain vs. Frequency and $P_{\text{IN}}$

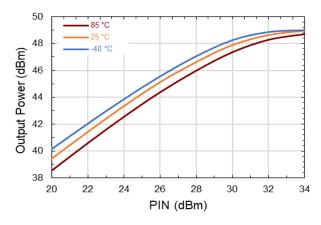




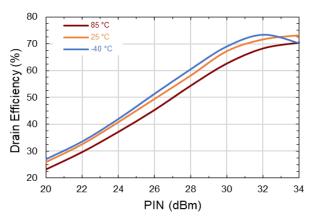
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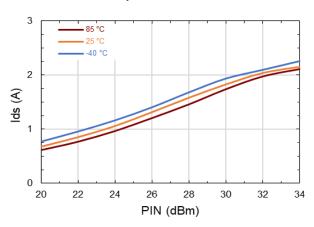
#### Output Power vs. Temperature and PIN



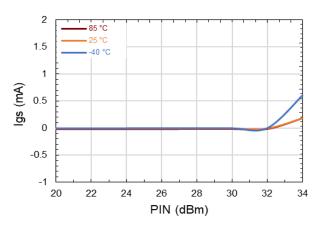
## Drain Efficiency vs. Temperature and $P_{IN}$



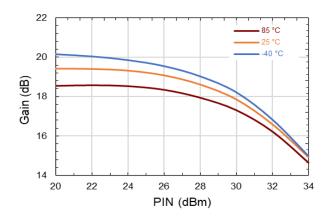
#### Drain Current vs. Temperature and PIN



Gate Current vs. Temperature and PIN



#### Large Signal Gain vs. Temperature and PIN

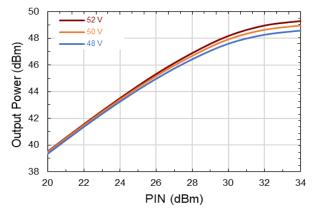




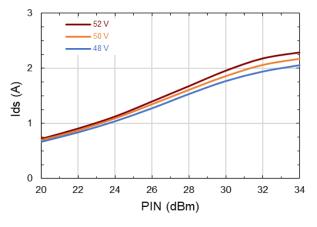
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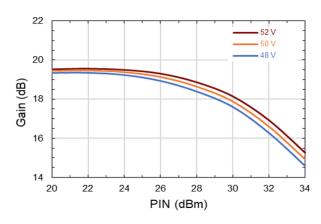
#### Output Power vs. VDS and PIN



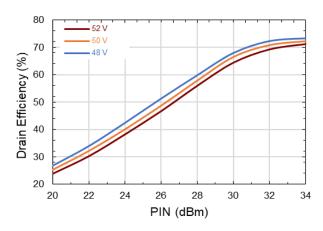
## Drain Current vs. V<sub>DS</sub> and P<sub>IN</sub>



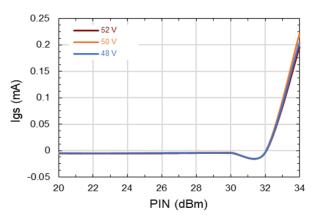
#### Large Signal Gain vs. VDS and PIN



#### Drain Efficiency vs. V<sub>DS</sub> and P<sub>IN</sub>



Gate Current vs. VDS and PIN

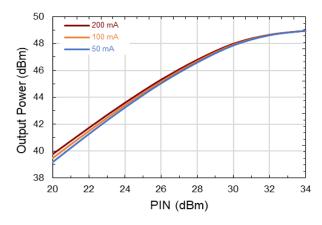




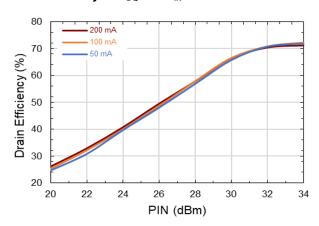
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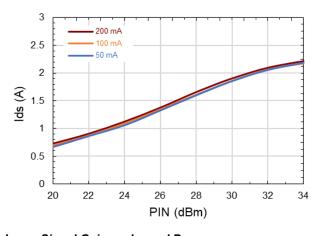
#### Output Power vs. IDQ and PIN



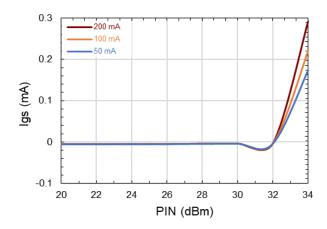
#### Drain Efficiency vs. IDQ and PIN



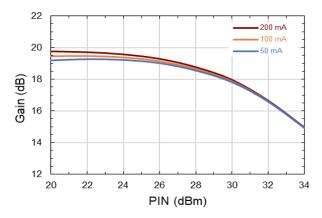
#### Drain Current vs. IDQ and PIN



Gate Current vs. IDQ and PIN



#### Large Signal Gain vs. $I_{DQ}$ and $P_{IN}$

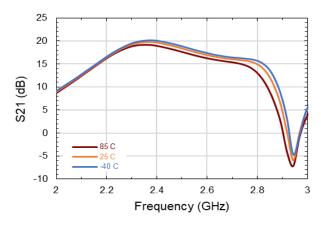




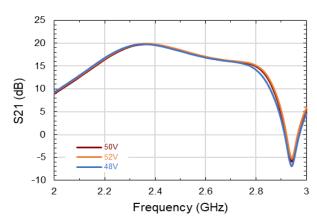
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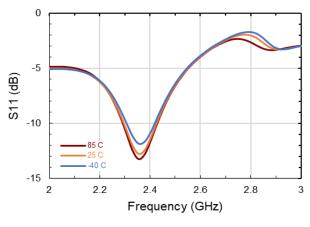
#### S21 vs Frequency and Temperature



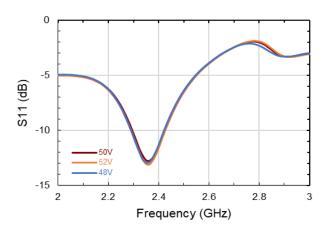
#### S21 vs Frequency and V<sub>DS</sub>



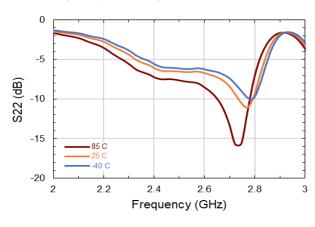
#### S11 vs Frequency and Temperature



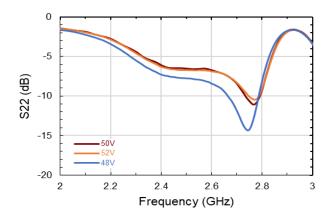
S11 vs Frequency and V<sub>DS</sub>



#### S22 vs Frequency and Temperature



S22 vs Frequency and V<sub>DS</sub>

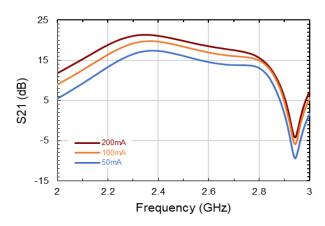




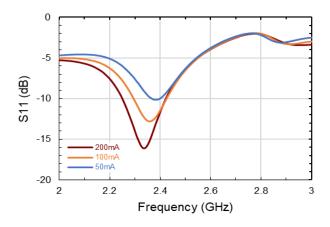
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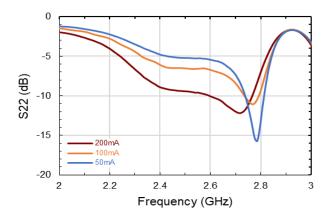
#### S21 vs Frequency and IDQ



#### S11 vs Frequency and IDQ



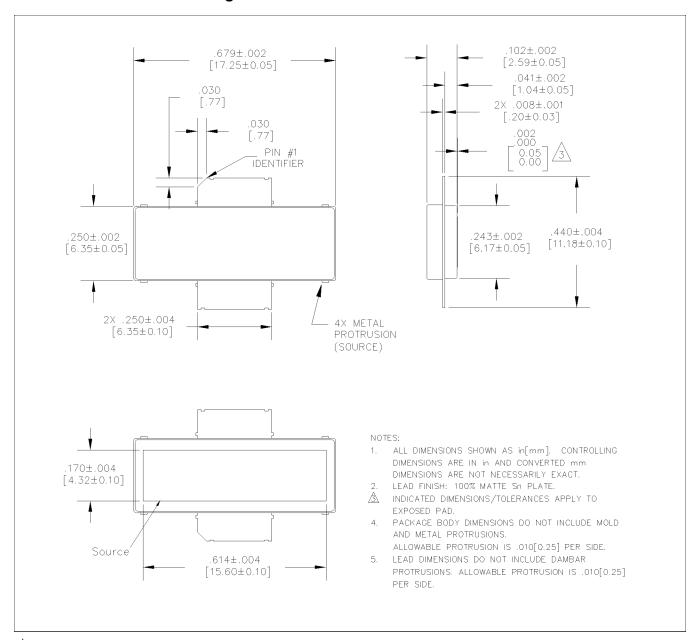
#### S22 vs Frequency and IDQ





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## Lead-Free TO-272S-2 Package Dimensions<sup>†</sup>



<sup>&</sup>lt;sup>†</sup> Reference Application Note AN0004125 for lead-free solder reflow recommendations. Meets JEDEC moisture sensitivity level 3 requirements. Plating is Matte Sn.

## GaN Amplifier 50 V, 50 W DC - 2700 MHz



MAPC-A1110-AP

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